



# The Fundamental Technical Knowledge of Passive Components

— for Windows version —

**Chapter I : Capacitor**

**Chapter II : Inductor**

**Chapter III : Electro-Magnetic  
Compatibility (EMC)**

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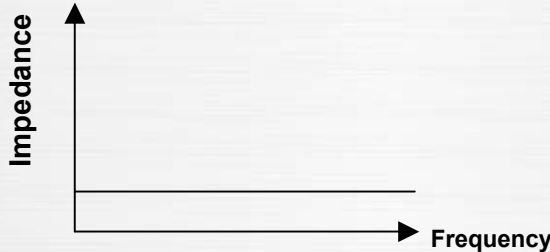
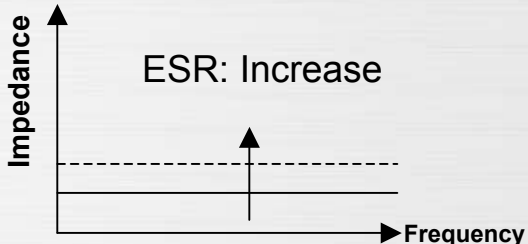

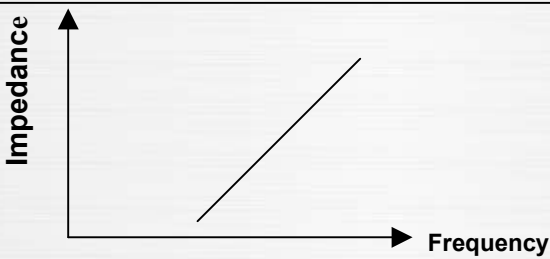
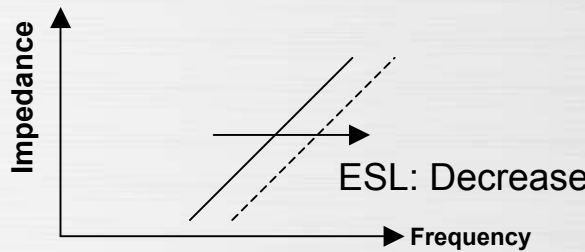

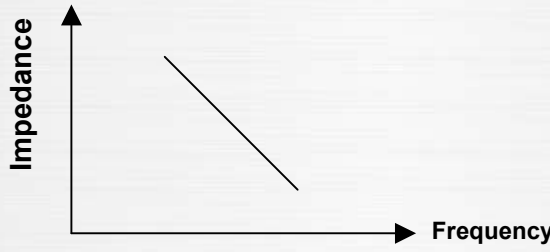
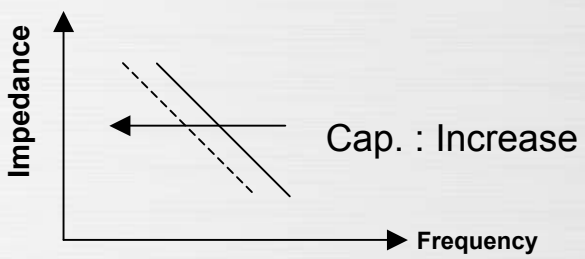


**- Chapter 1 -**

# **Capacitor**

# Impedance Characteristics of Capacitor

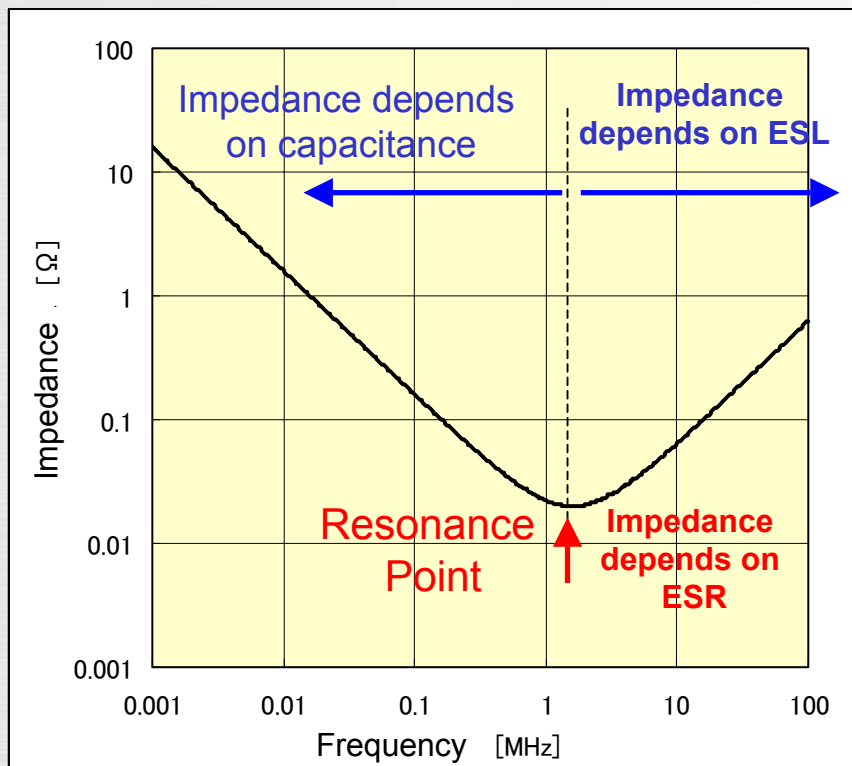
**Impedance equivalent circuit with capacitor is the same as the RLC series model.**

Elements in Capacitor	Changes in Frequency	Changes in Element
ESR 	 <p>ESR is constant</p>	 <p>ESR: Increase</p>
ESL 	 <p>ESL increases</p>	 <p>ESL: Decrease</p>
Capacitance 	 <p>Capacitance decreases</p>	 <p>Cap. : Increase</p>

**What happens to the impedance level when connected in series?**

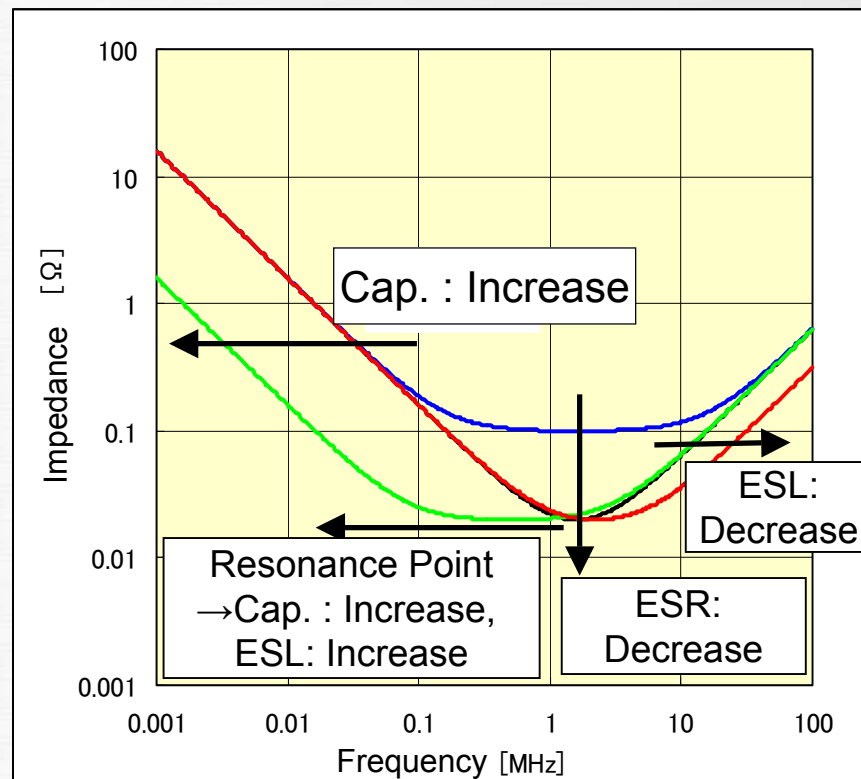
# Impedance Characteristics of Capacitor

## Impedance for series connection



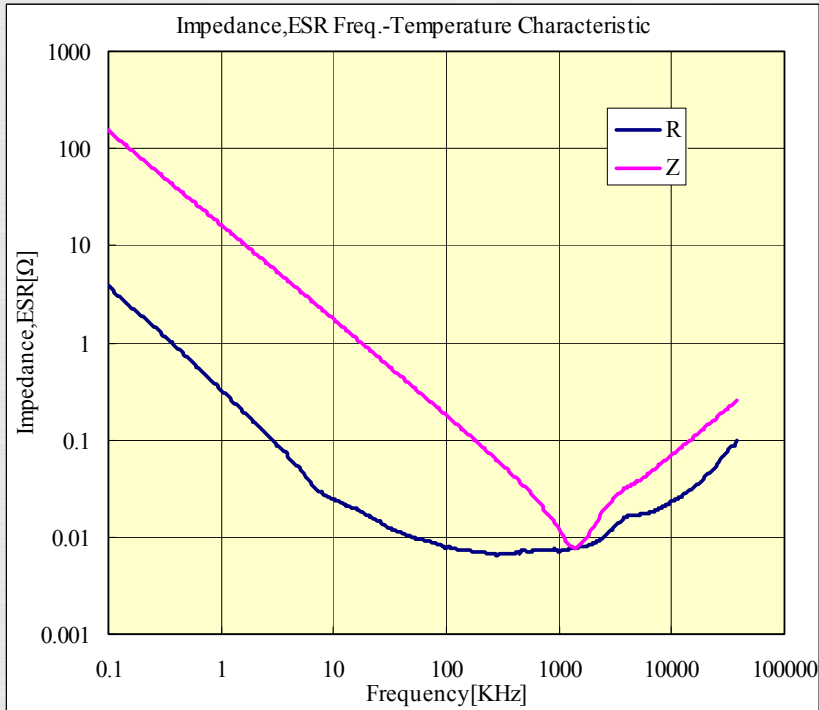
- At resonance point, no impedance for Capacitor & ESL (Impedance for ESR only)
- The frequency at resonance point depends on Capacitor & ESL

## Impedance with different elements



Impedance characteristics vary depended on each element.

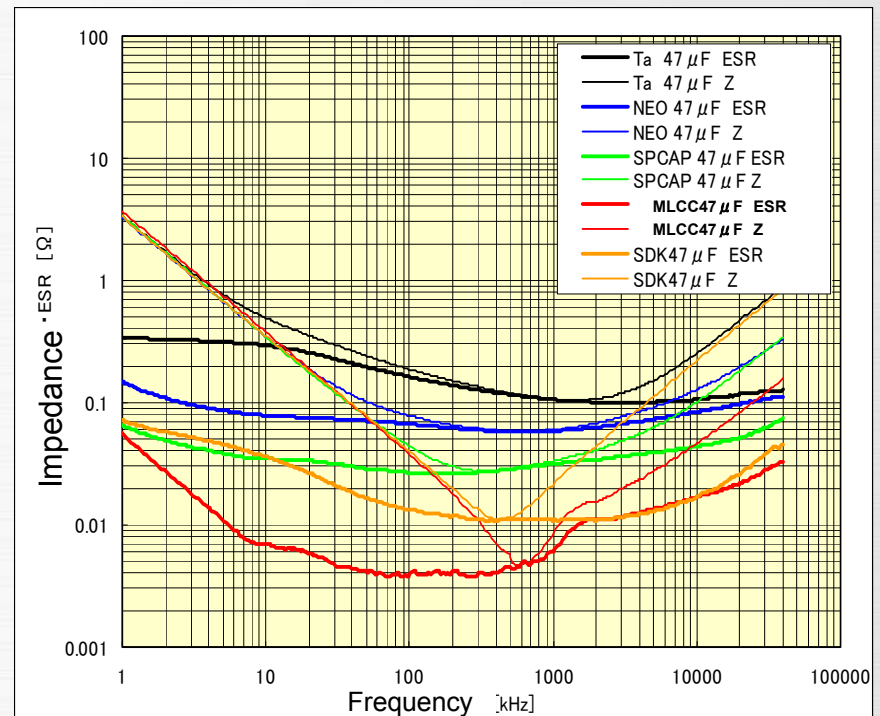
## ESR varies depended on frequency



RLC Series Model → ESR independent from frequency

**ESR actually varies.**

## Frequency characteristics for different type of capacitors



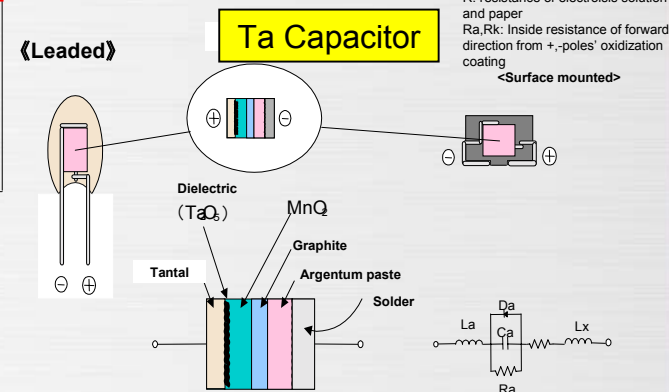
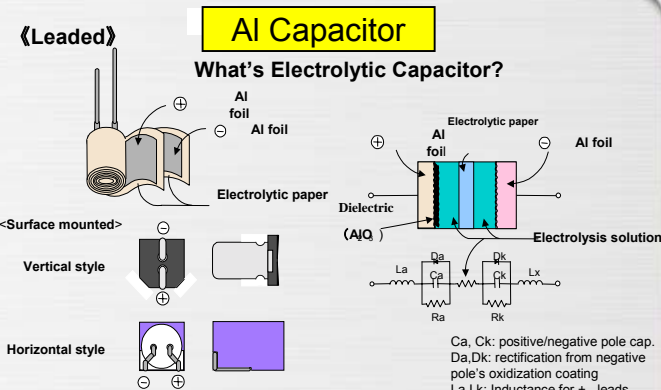
RLC varies depended on capacitor's material, structure and case size

**Frequency characteristic varies depended on the type of capacitor, especially on ESR.**

# Reliabilities of Multi-Layered Ceramic Capacitor

## 1. Operational condition comparison chart for Circuit

	Polarity	De-rating	Ripple CU. Limitation	Heat Resistance	Solvent Resistance	Loading Test
MLCC	No	◎	◎	◎	◎	◎
Ta Cap.	Yes	×	△	×	△	×
Al Cap.	Yes	×	×	△	×	△
Application Problems	*Layout *Polarity exam When mounting *Reverse voltage Consideration	*Operational limitation for rated voltage (70~50%level)	*Have margin capacity for ripple current *Less reliable associated from self heating	*Limitation for reflow molding and degrading advancement	*Liquid solution flooding except block structure MLCC	*Al capacitor: decreasing in capacitance from electrolysis loss *Ta capacitor: diffusion of Ag, short circuit from degrading of insulating layer

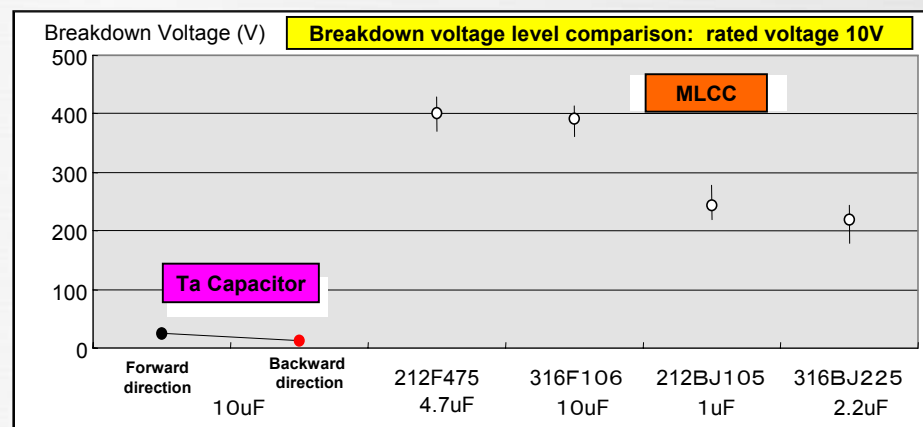


## Ceramic Capacitor

Dielectric:  
Barium Titanate

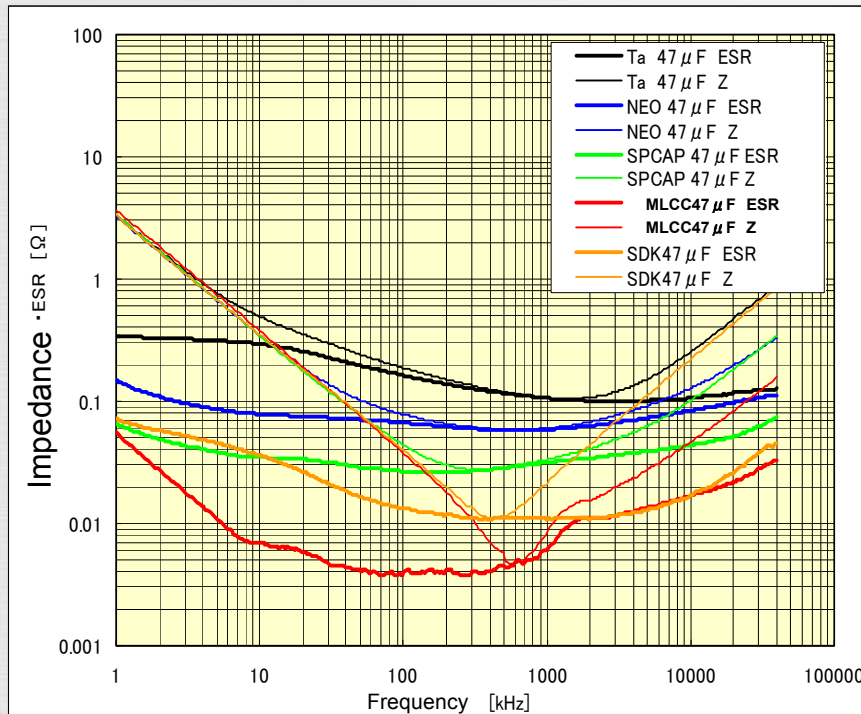


Electrode: Ni



# Characteristics Comparison for the Different Type of Capacitors

## Frequency Characteristics



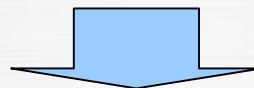
ESR varies greatly depended on each type of capacitors.

Al>Ta>Functional Ta>Functional Al>ML

The lower ESR becomes, the lower the impedance for high frequency gets.

Al>Ta>Functional Ta>Functional Al>ML

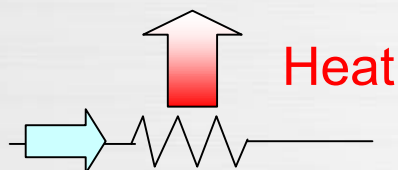
MLCC has superior frequency characteristics.



**The most competitive merit**

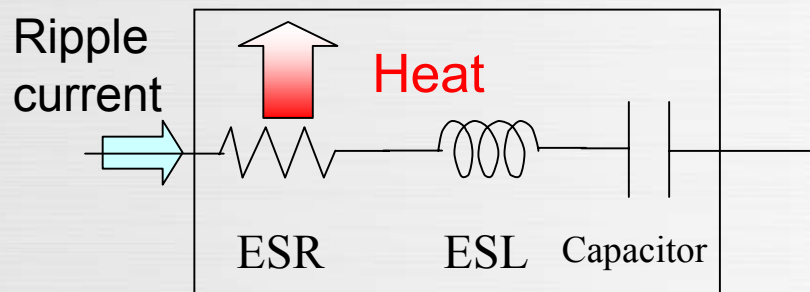
# Characteristics Comparison for the Different Type of Capacitors

## Ripple Current Characteristics



Electrical energy is converted to heat when current goes through resistance.

## Capacitor

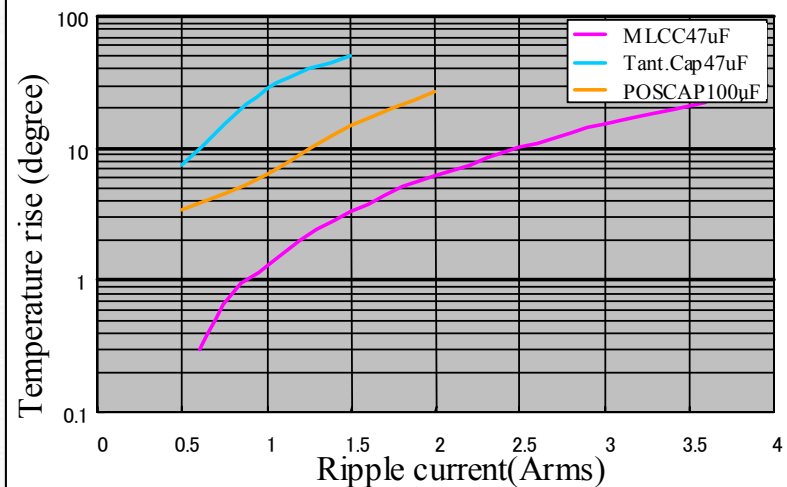


Electrical energy is converted to **heat** when **ripple current** (AC) goes through capacitor. (DC does not go through it)

**Heat** shortens capacitor's durability.

## Ripple current characteristics for the different type of capacitors

Temperature rise characteristic due to ripple current



Given the same amount of calorific power, **ripple current** goes through **MLCC** the most because of its **low ESR**.

Operational recommendation of **heat release value** for MLCC is **within 10°C**.  
There is no limitation of allowed ripple current for MLCC.

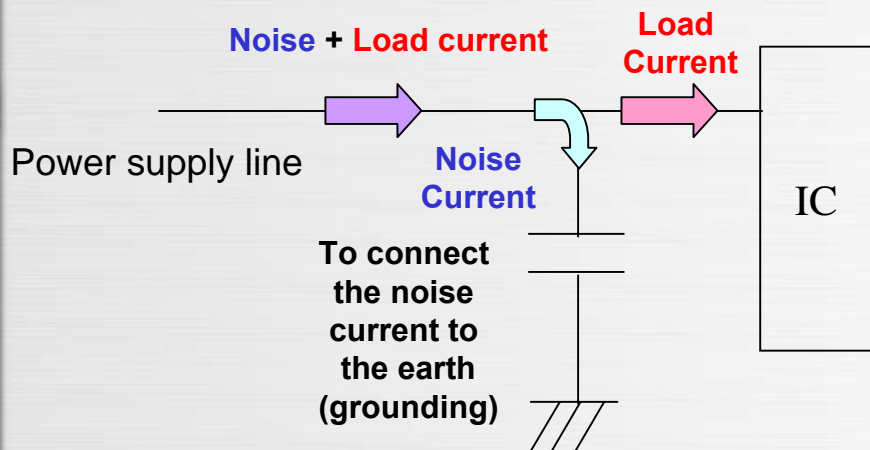
Operational recommendation of **heat release value** for **electrolytic capacitor** is **within 5°C**.  
Allowed ripple current is regulated by makers.



# **The Basic Knowledge of Circuits**

# The Functions of Bypass (decoupling) Capacitor

## The Role of Bypass Capacitor



## The principle of operation for Bypass Capacitor

DC does not go through the capacitor  
(Impedance:  $\infty$ )

➡ DC is supplied directly to IC

AC (noise) does go through the capacitor

➡ AC (noise) is grounded



Noise Suppression → Stabilize IC operation

## Necessary Characteristics for Bypass Capacitor

It has low impedance.

(low prevention of an electric current)



It electrifies an electric current well.



It efficiently grounds the noise current.



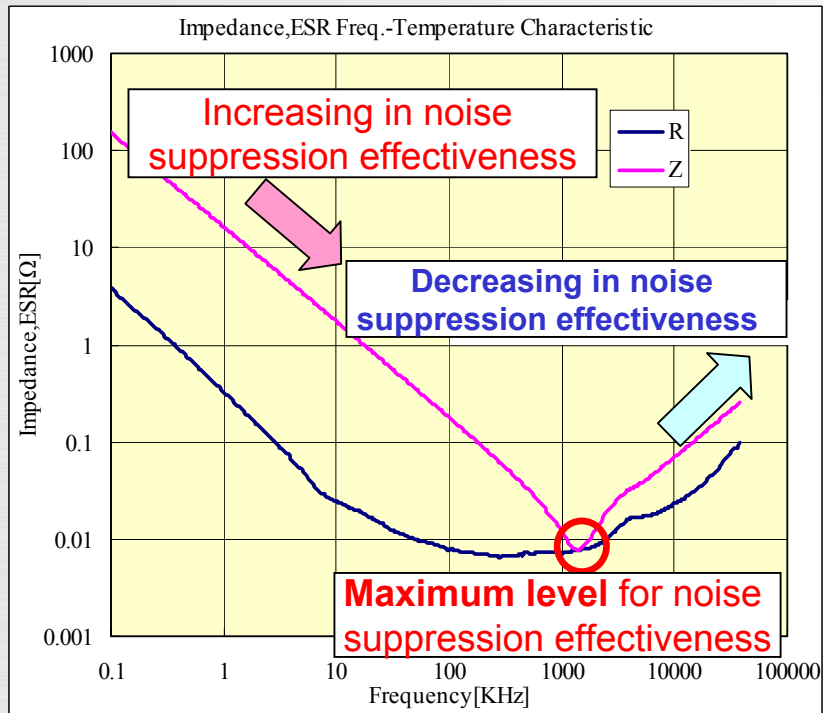
It effectively decreases the noise current.



Impedance	Low	↔	High
Noise effect of decreasing	More effective	↔	Less effective

# The Functions of Bypass (decoupling) Capacitor

## Selection Criteria for Capacitor

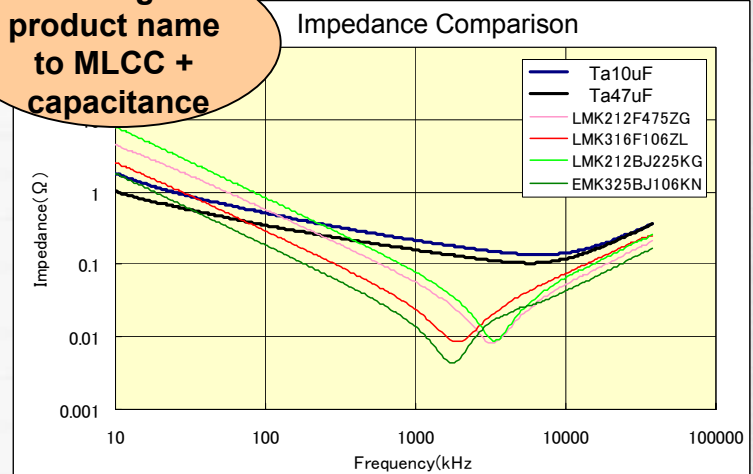


Several kinds of Noise Frequencies

Select a Capacitor based on noise frequency needs to be eliminated

## Replacement of Ta capacitor by Bypass Capacitor

Change product name to MLCC + capacitance



When the frequency is over 10kHz, the impedance of MLCC is lower than that of Ta capacitor.

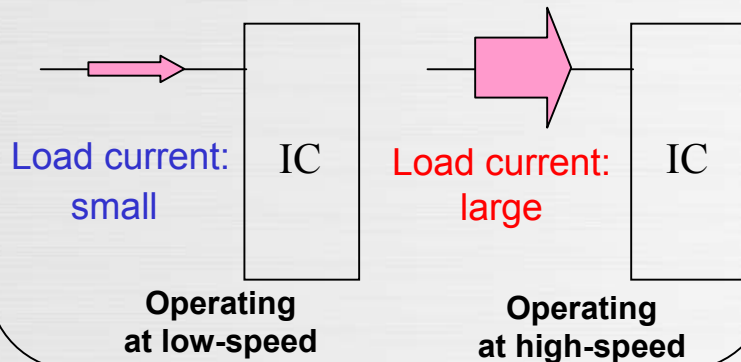
Effectiveness of reduction in high frequency noise for MLCC is more superior than that of Ta capacitor.

It enables to replace Ta capacitor with a smaller value of MLCC.

# The Functions of Backup Capacitor

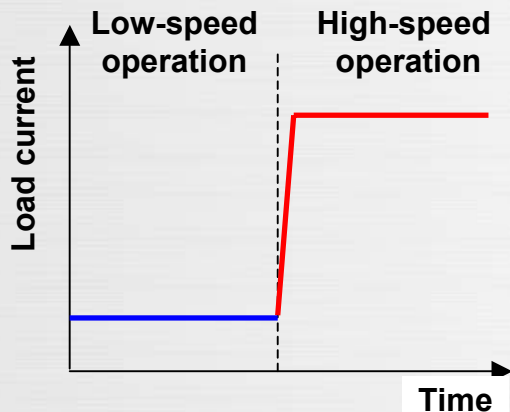
## Load current to IC

Load current doesn't stay constant.



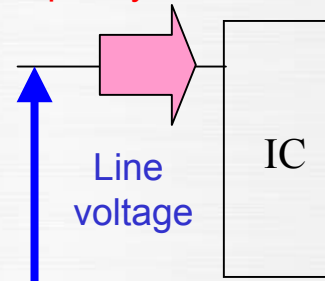
## High-speed load change

When IC's operational speed changes rapidly, **large load current is quickly needed.**

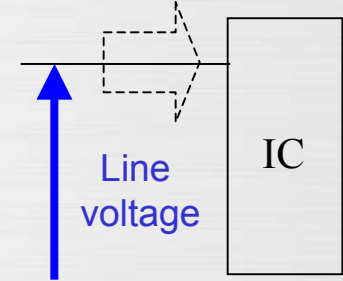


## Power line for high-speed load changing

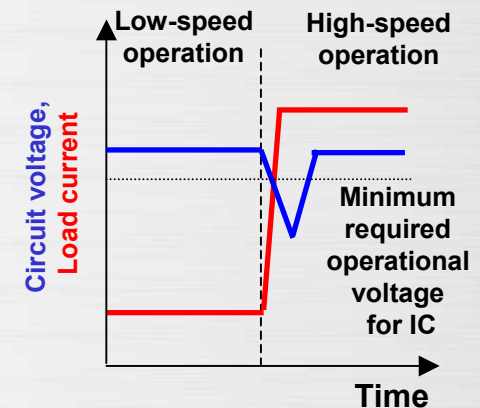
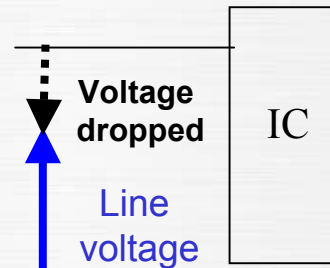
**Large load current is quickly needed.**



**The current can't flow to IC quickly enough.**



**Line voltage can't be maintained, therefore voltage is dropped.**

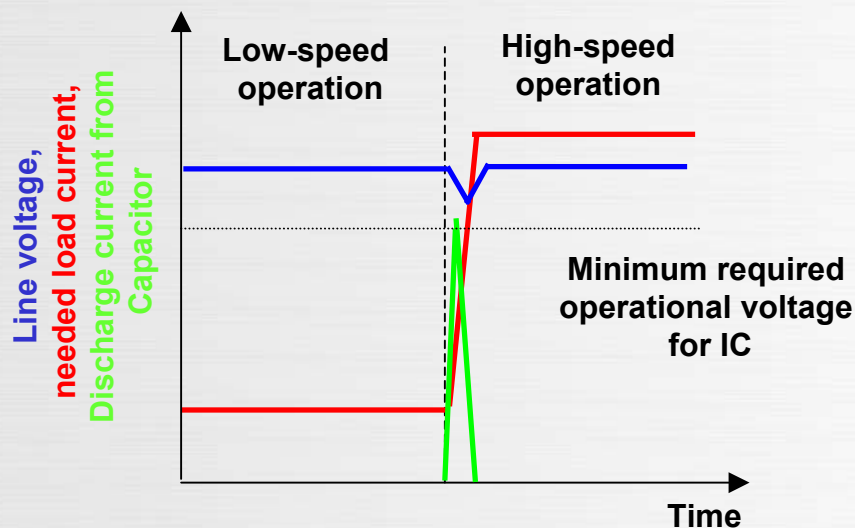
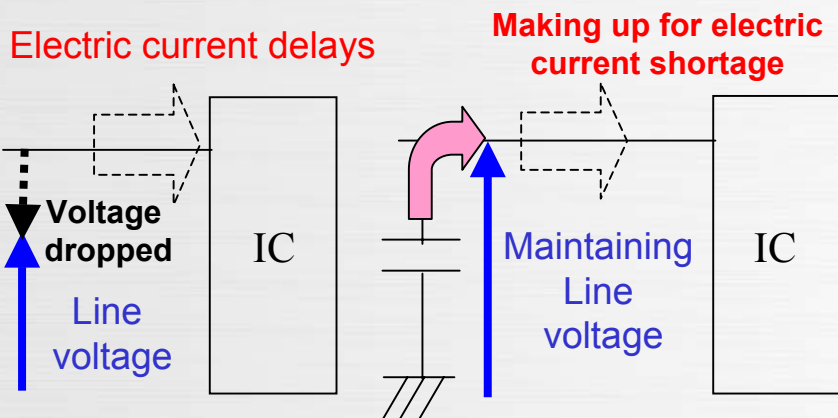


**Line voltage decreases below the required operational voltage for IC.**

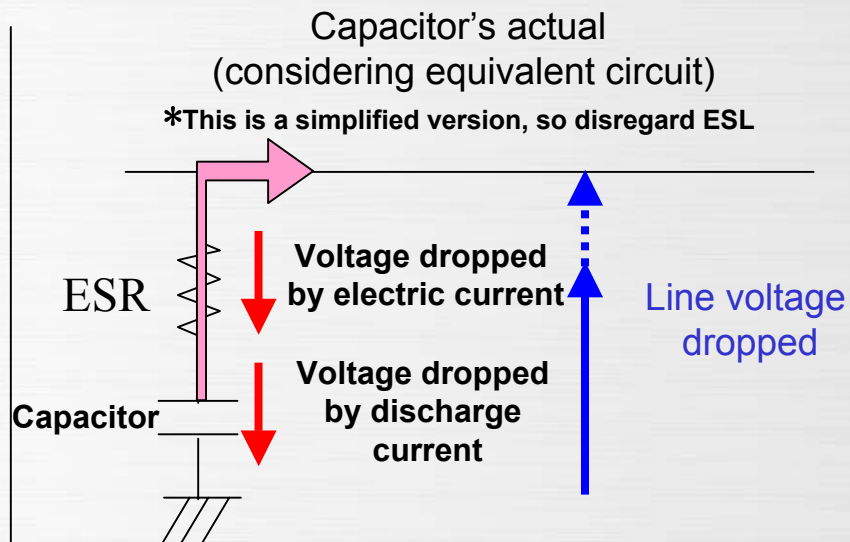
**The IC stops its operation.**

# The Functions of Backup Capacitor

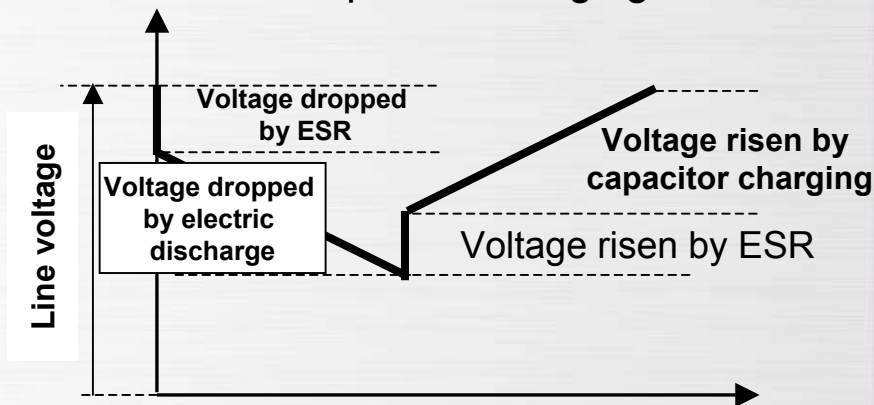
## The Role of Backup Capacitor



Keeping the minimum required operational voltage for IC → Maintaining stable operation

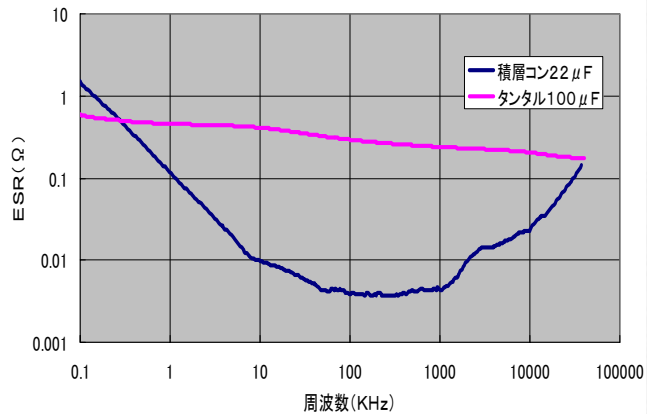
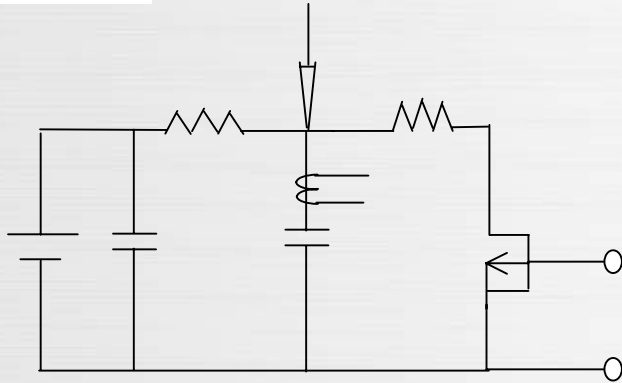


Voltage fluctuation occurs when capacitor charging



Capacitor and ESR decide the amount of voltage dropped

# The Functions of Backup Capacitor













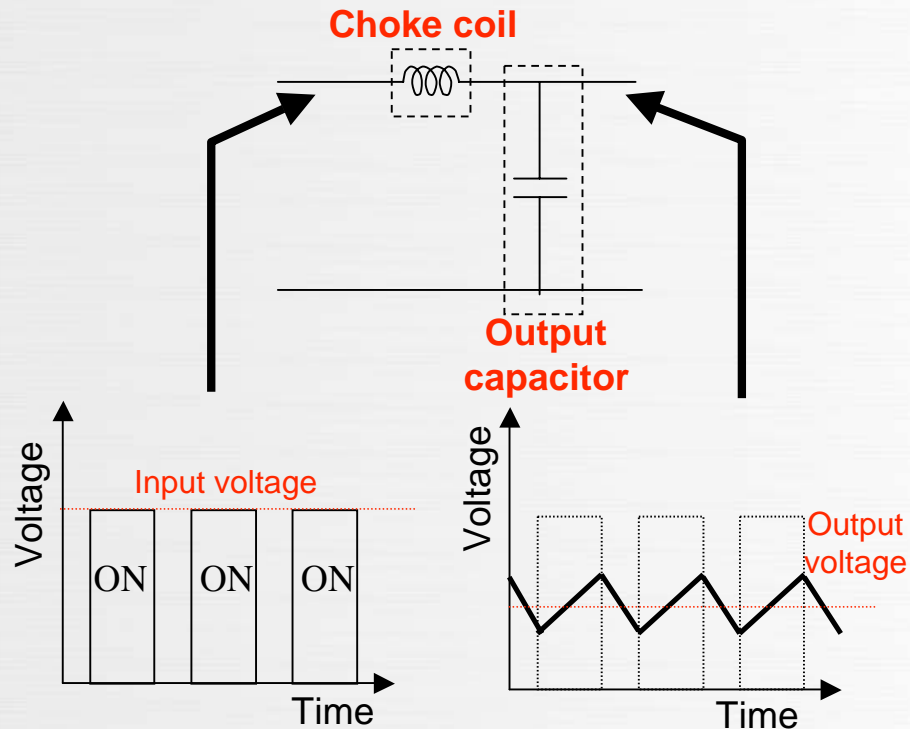






# Step-Down Converter

## Output side operation



Input voltage is controlled by an on-off switching.

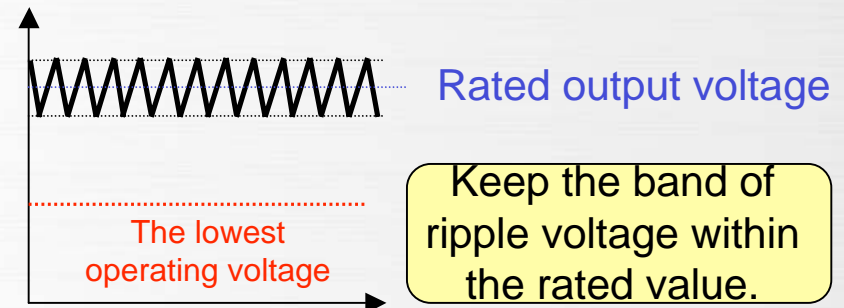
It is smoothed with a choke coil and an output capacitor.

**Ripple voltage is included.**

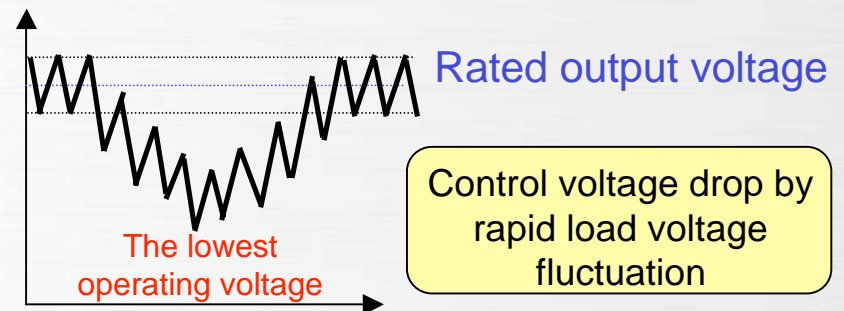
## Points of output voltage to remember

Keeping higher voltage than **the lowest operating voltage** of load IC.

### Ripple voltage



### Rapid load voltage fluctuation









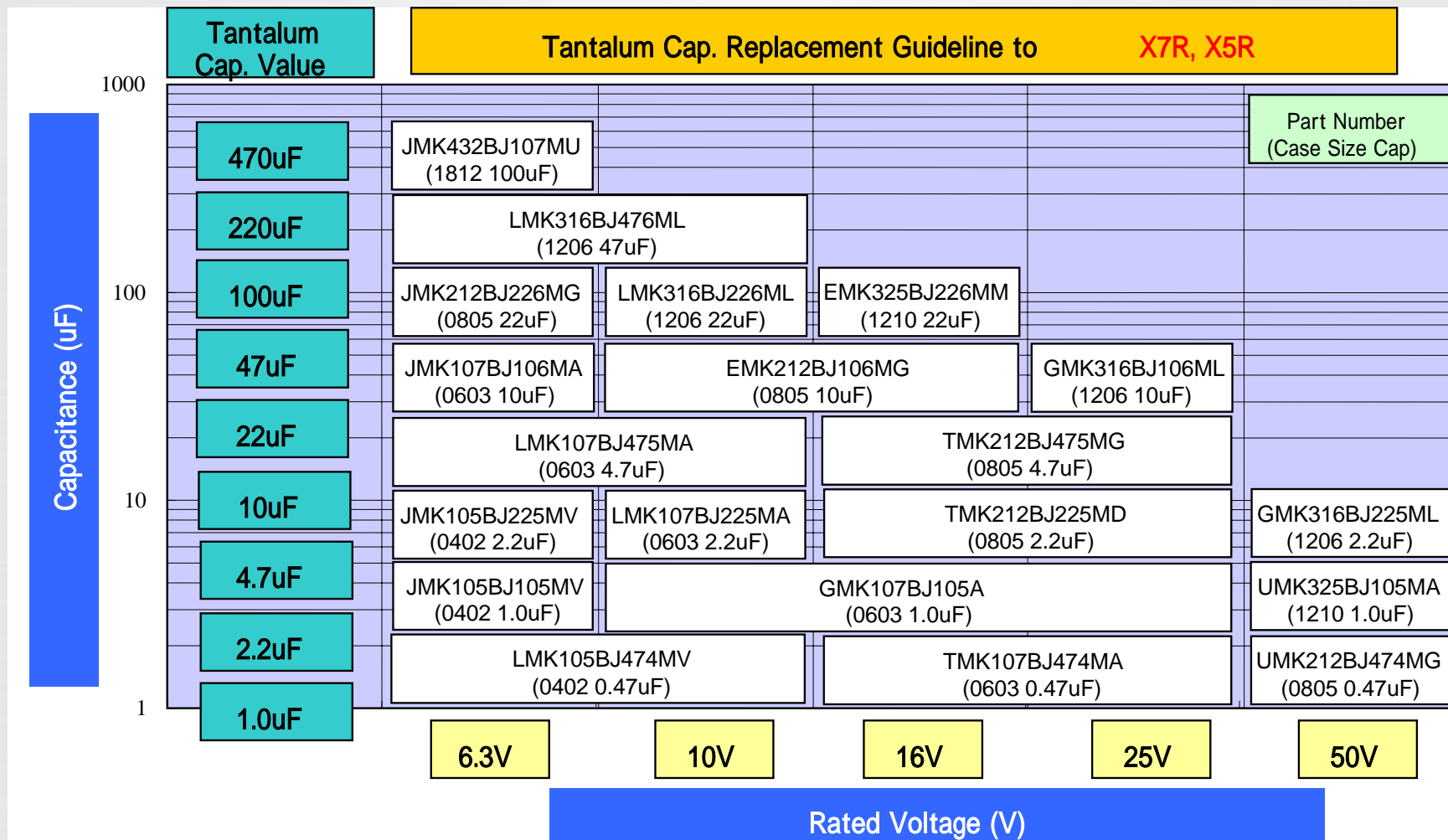








# Ta cap & Al cap replacement guideline to MLCC X7R, X5R



Note: Suggested capacitance value of MLCC may be changed depending on the frequency level of noise.

Note: As derating is not required for MLCCs, use the actual voltage of the circuit when selecting MLCC for replacement.

**It requires as much as 1/5 to 1/20 of Al capacitor's capacitance to replace.**













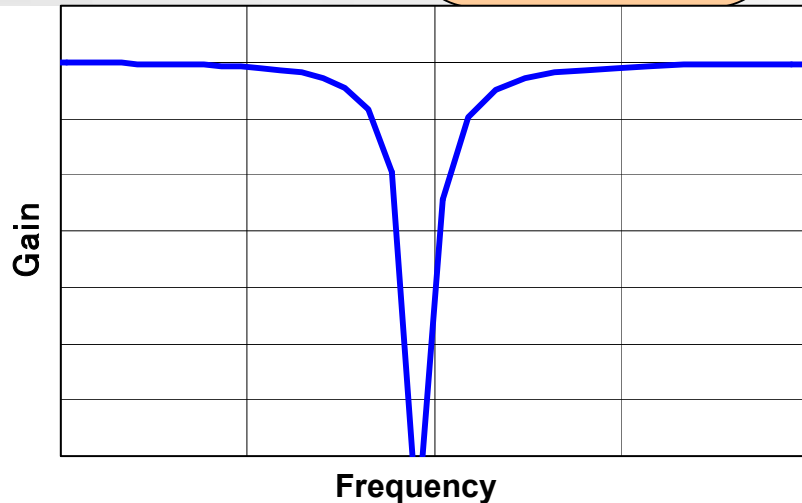
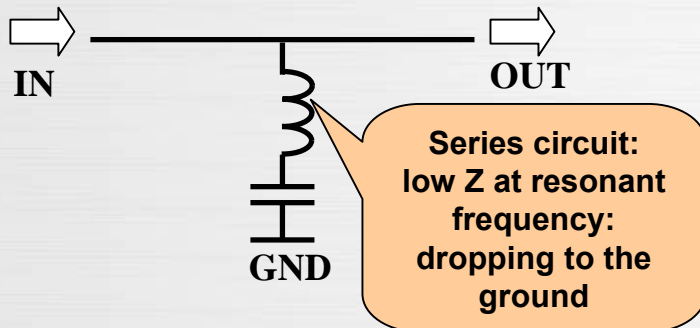


# Application of Inductor and Capacitor “Band-pass Filter and Trap Filter”

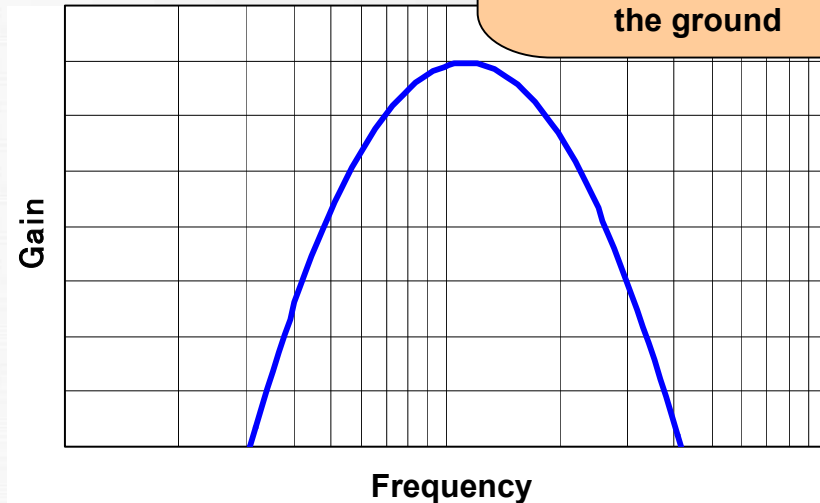
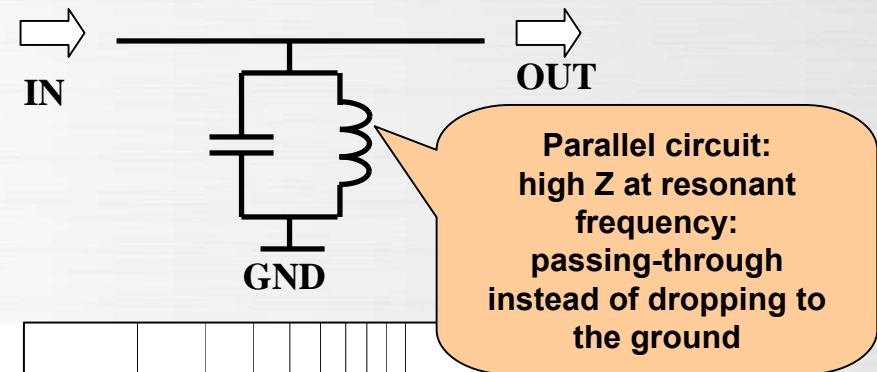
Impedance of series circuit: **Lowest** at frequency resonance point

Impedance of parallel circuit: **Highest** at frequency resonance point

Typical characteristic of trap filter

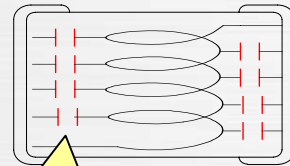
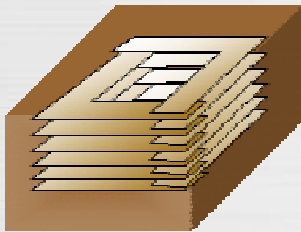


Typical characteristic of band-pass filter



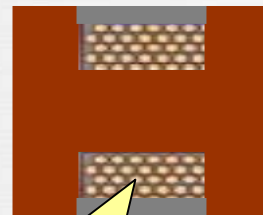
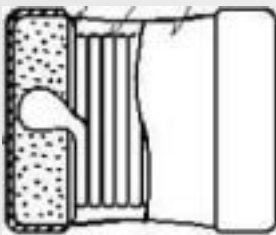
# Real Characteristics of Inductor “Self-Resonance Point Characteristic”

## Multilayer inductor



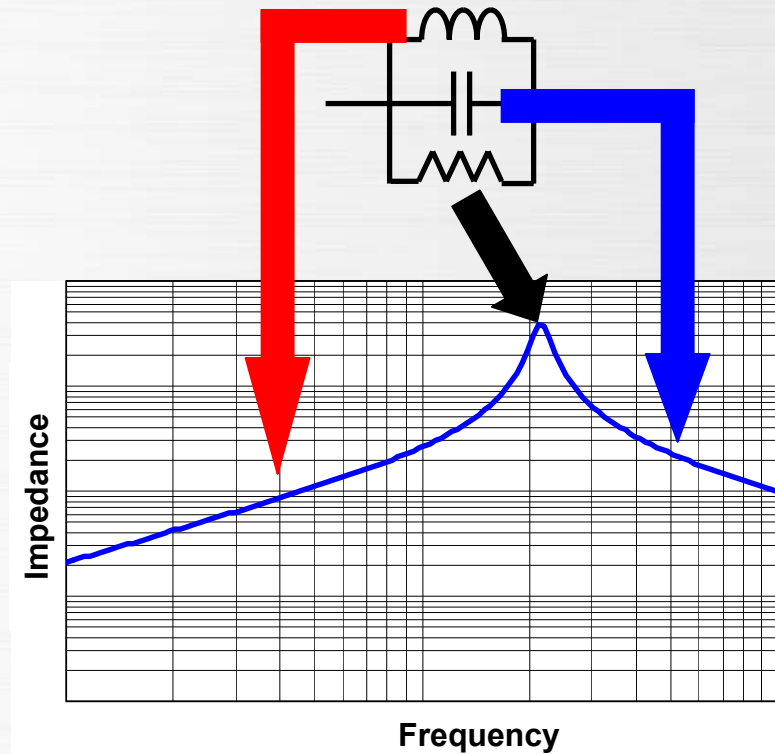
Ex) **Stray capacitance** existed between internal and external electrode

## Wound chip inductor



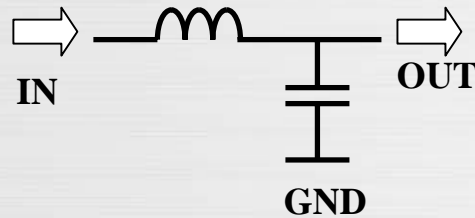
Ex) **Stray capacitance** existed between winding wires

Typical impedance characteristic of existing inductor  
~similar to the typical impedance characteristic of LCR parallel circuit~

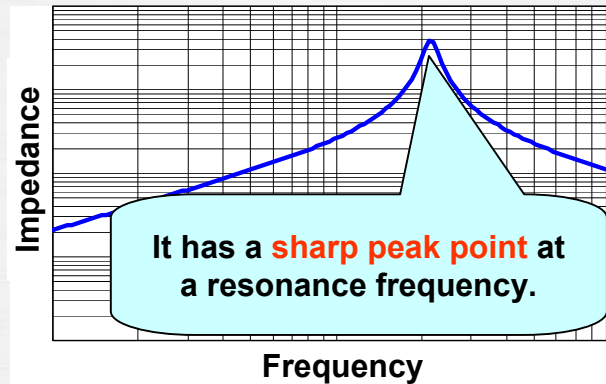


**Inductor** for the low frequency side,  
**capacitor** for the high frequency side and  
at resonance point, impedance is limited.

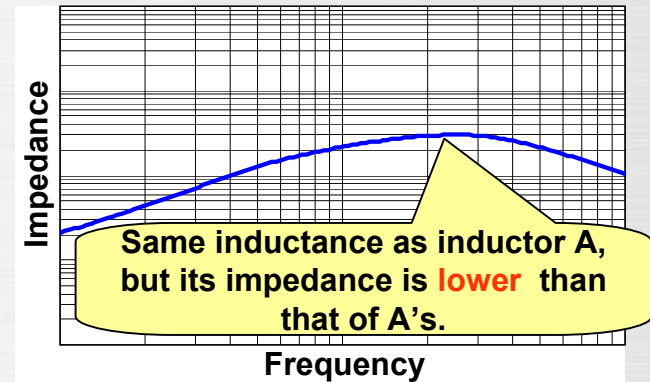
### Example of Low-pass filter



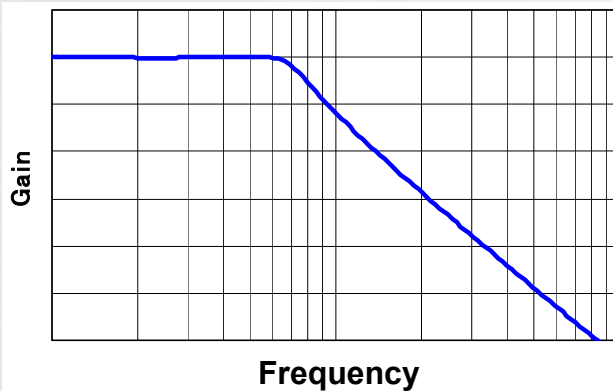
#### Inductor A: impedance characteristic



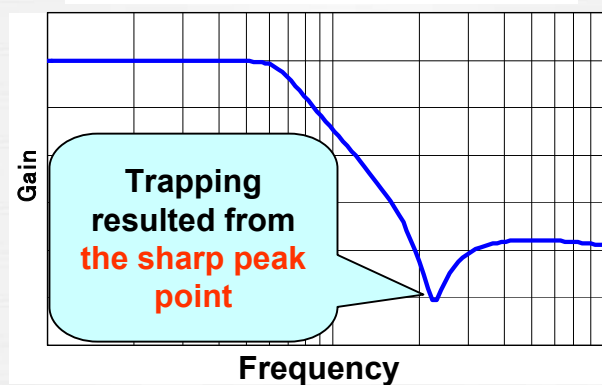
#### Inductor B: impedance characteristic



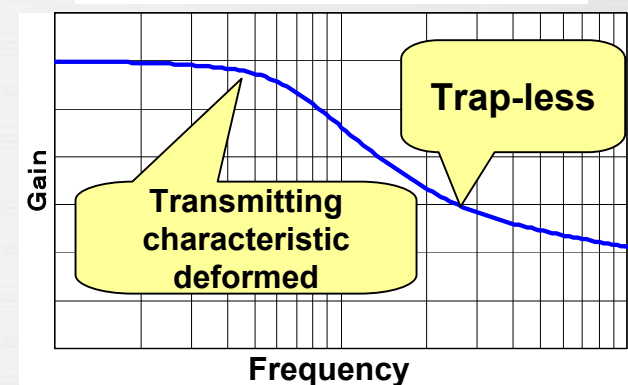
#### Filter characteristic of pure inductor



#### Inductor A in use



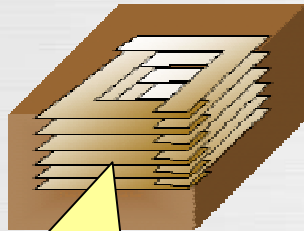
#### Inductor B in use



This **self-resonance characteristic** is **proactively implemented** for a filter circuit application, and therefore this unique characteristic needs to be considered for both replacement and downsizing applications.

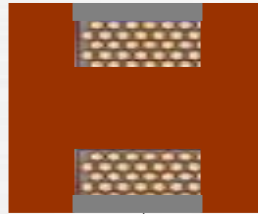
# Real Characteristics of Inductor “Lost Elements and Q Characteristic”

ML inductor



Print internal electrode  
on sheet made of core  
material

Wound chip inductor



Wind up wire  
around core

Inductor's Q factor

Impedance of pure inductor:  
**Inductive reactance**

Resistance  
elements  
(Summation of loss)



**Q**

$$Q = \frac{\text{Inductive reactance}}{\text{Resistance elements}}$$

## Core materials:

Hysteresis loss, Eddy current loss, dielectric material loss and more ...

## Internal electrode:

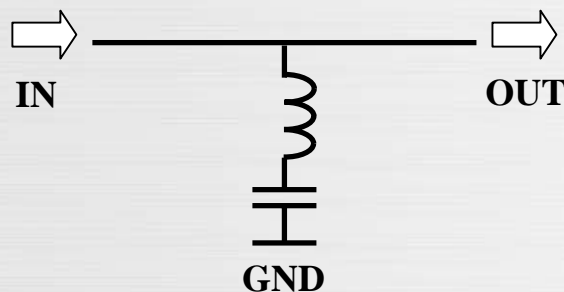
DCR, resistance loss in high frequency zone originated from skin effect and more...

Pure inductor has no loss at all.

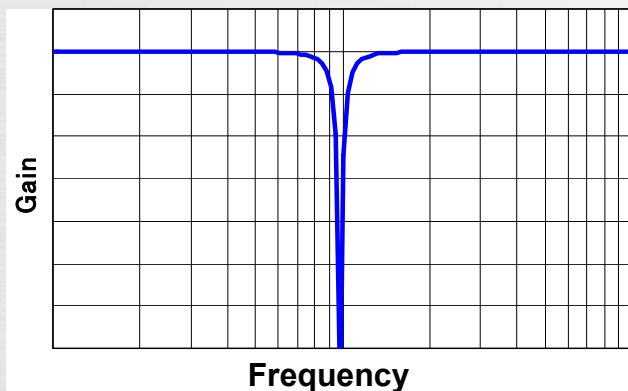
Q factor is an approximation value which expresses how close an inductor is to be a pure inductor.

The larger the Q factor an inductor has, the purer the inductor becomes on circuit.

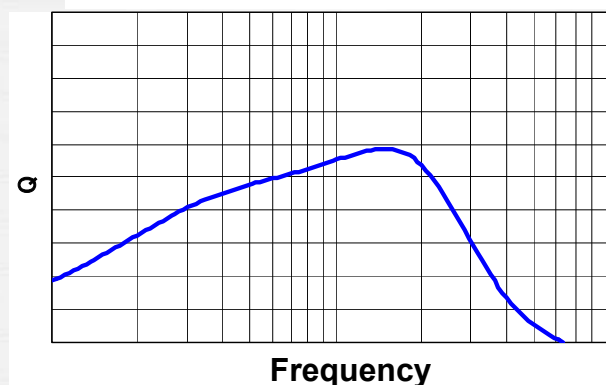
Example of trap filter  
Series resonance of inductor and capacitor



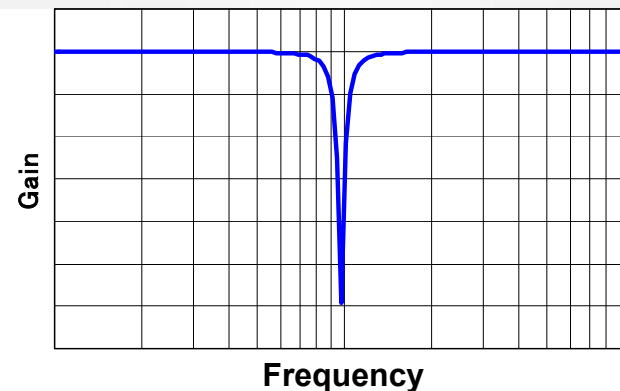
Filter characteristic example  
of pure inductor



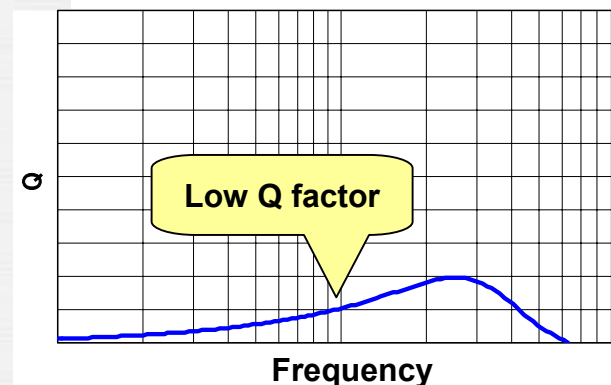
Inductor A: Q factor characteristic



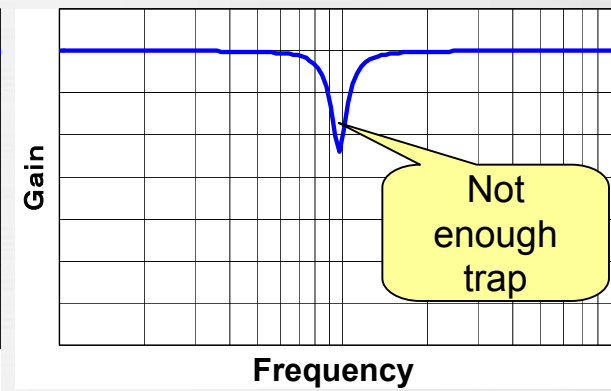
Inductor A in use



Inductor B: Q factor characteristic



Inductor B in use

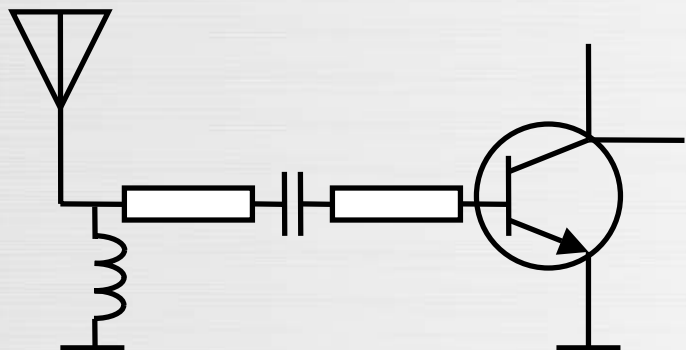


In case of **resonance circuit** with capacitors, generally inductor's **Q factor characteristic** has huge influence on the circuit.

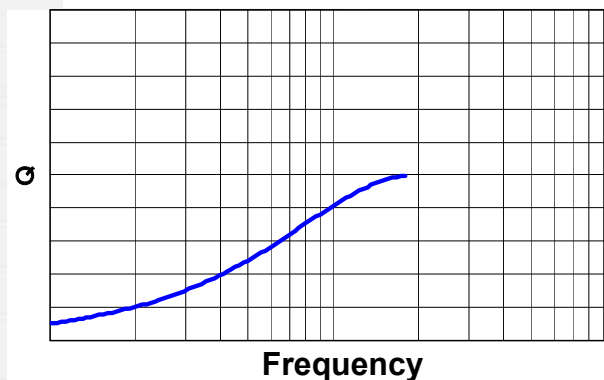


# Q-Value and Matching Characteristics “Example of How the Difference in Q-value Influences Matching Characteristic”

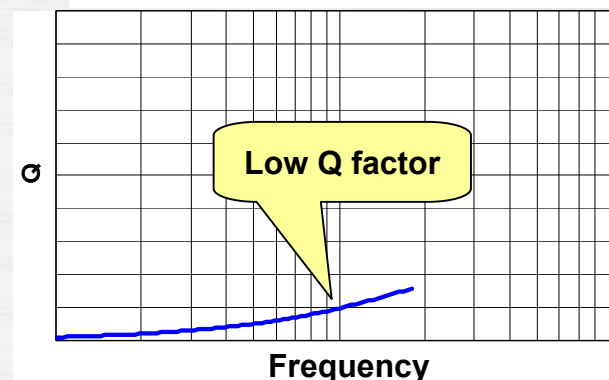
Example of matching circuit  
Matching for amplifier and antenna



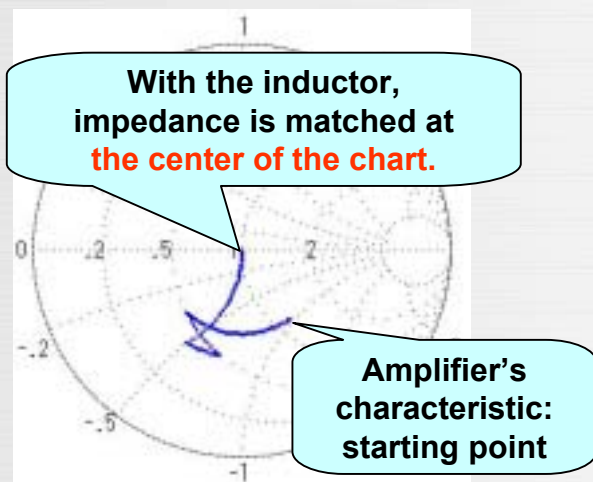
Inductor A: Q factor characteristic



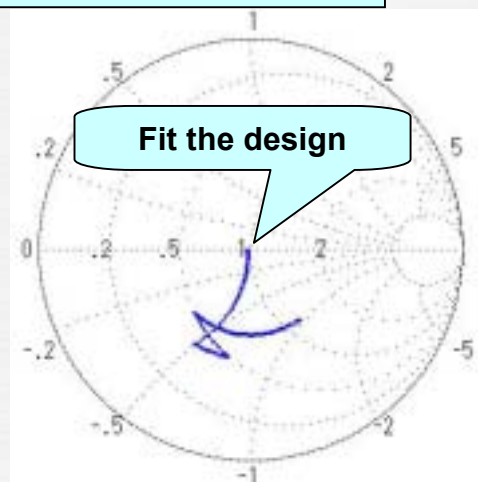
Inductor A: Q factor characteristic



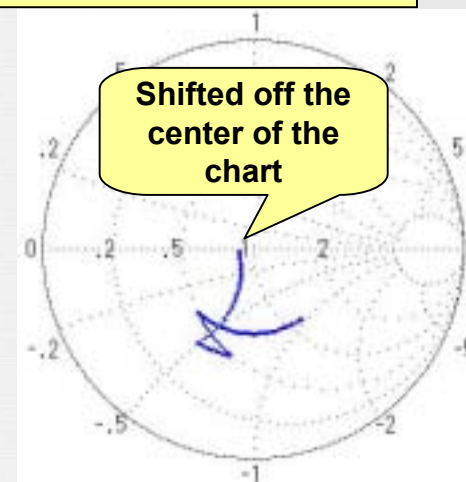
Example of matching design  
with pure inductor



Inductor A in use



Inductor B in use



In case of **matching** circuit, generally inductor's **Q factor** characteristic has huge influence on the circuit.

# Coffee Break “Q Factor of Inductor and Tan $\delta$ of Capacitor”

Q factor of inductor  
inductor's loss elements

Impedance of pure inductor:  
**inductive reactance**

Resistance  
elements  
(summation of loss)



$$Q = \frac{\text{Inductive reactance}}{\text{Resistance elements}}$$

Q factor is an approximation value which expresses how **close** an inductor is to be a pure inductor.  
The **larger** the Q factor an inductor has, the purer the inductor becomes on circuit.

Tan  $\delta$  of capacitor  
capacitor's loss elements

Impedance of pure capacitor:  
**Capacitance reactance**

Resistance  
elements  
(summation of loss)



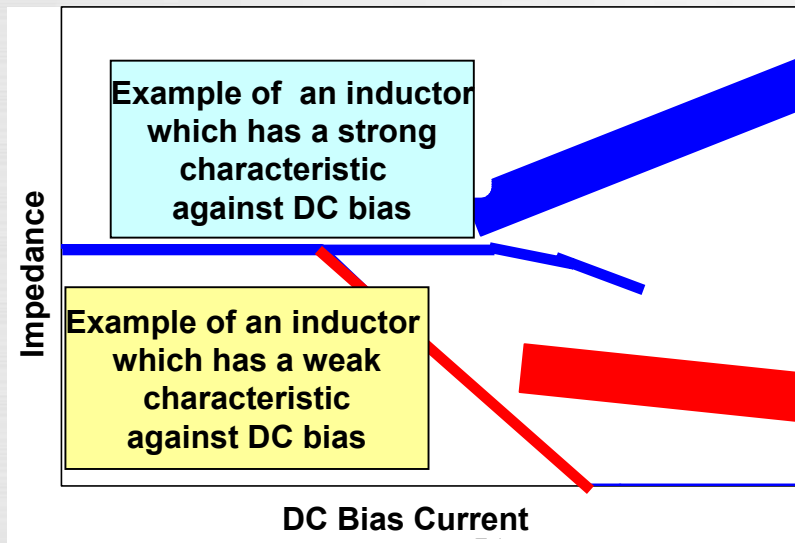
$$\text{Tan } \delta = \frac{\text{Resistance elements}}{\text{Capacitance reactance}}$$

Tan  $\delta$  is a value which explains how **far** a capacitor is from being a pure capacitor.  
The **smaller** the tan  $\delta$  a capacitor has, the purer the capacitor becomes on circuit.

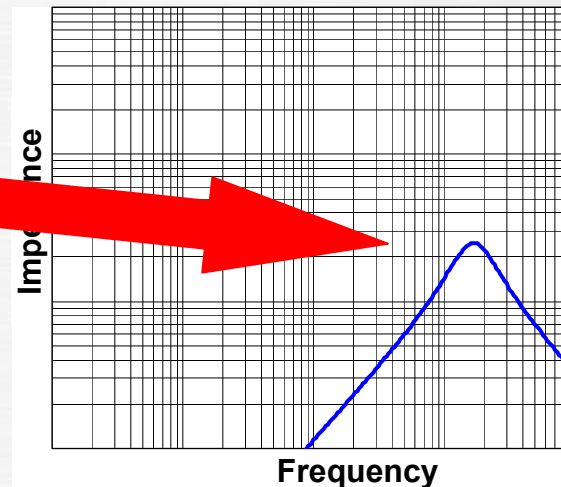
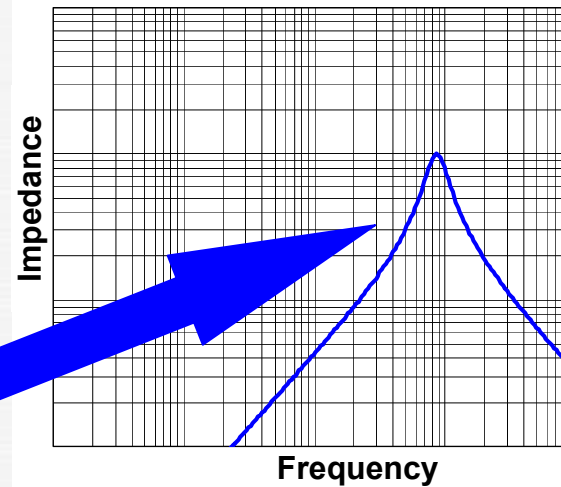
# Real Characteristics of Inductor “Example of DC Bias Characteristic”

## Example of inductor's DC bias characteristic

In case of magnetic-material core which has the magnetic saturation characteristic, inductance is lowered by increasing in DC bias current.



## Example of impedance characteristic



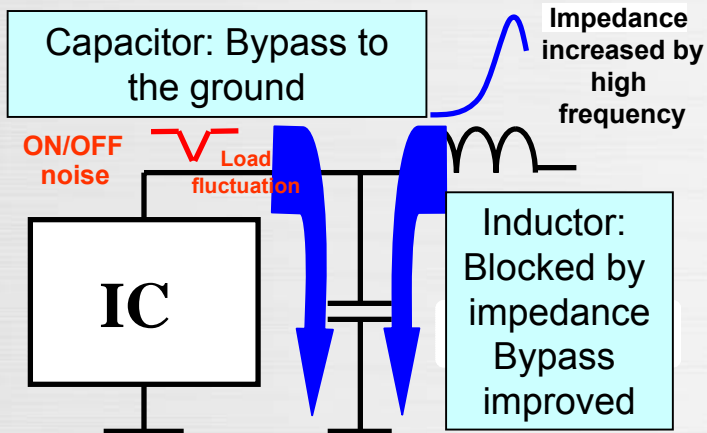
Impedance gets lowered as inductance is dropped by magnetic saturation.

An inductor which has a strong characteristic against DC bias can maintain high impedance level (vice versa).

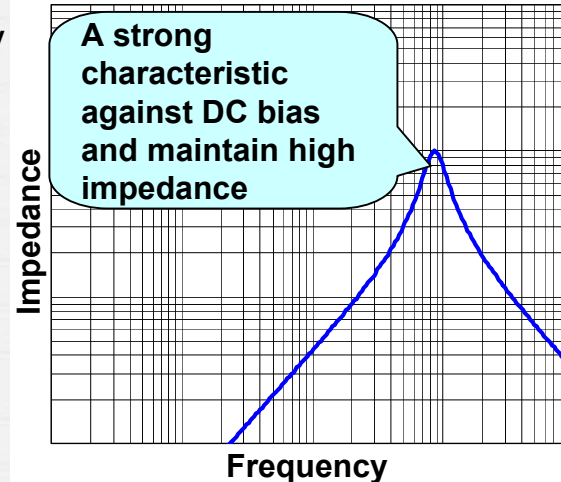
Generally, an inductor is selected based on a margin level for both required inductance and impedance under operational circumstances.

# Example of the Influence on Inductor's DC Bias Characteristic in use of Power Supply Choke

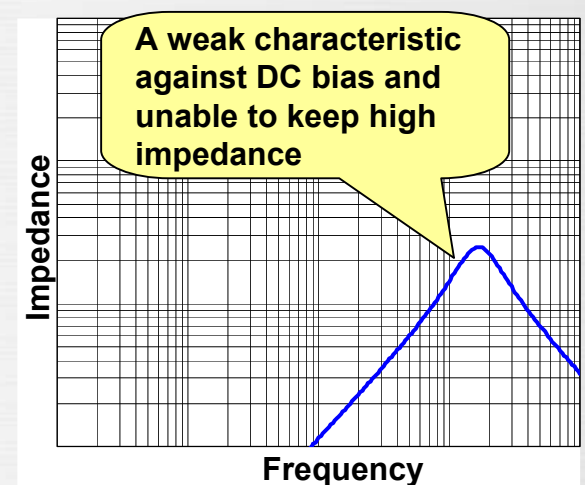
## Example of power supply choke circuit



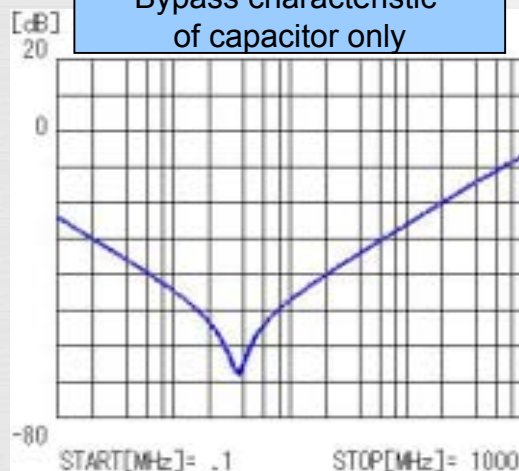
## Inductor A: Impedance characteristic



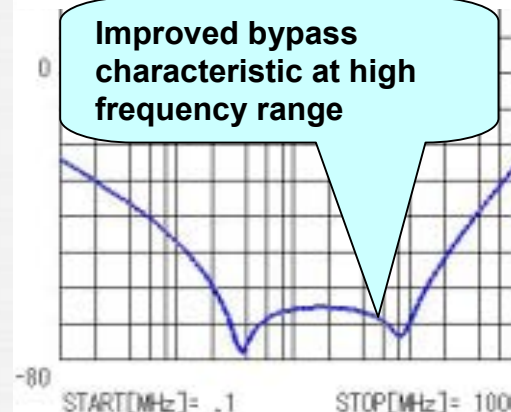
## Inductor B: Impedance characteristic



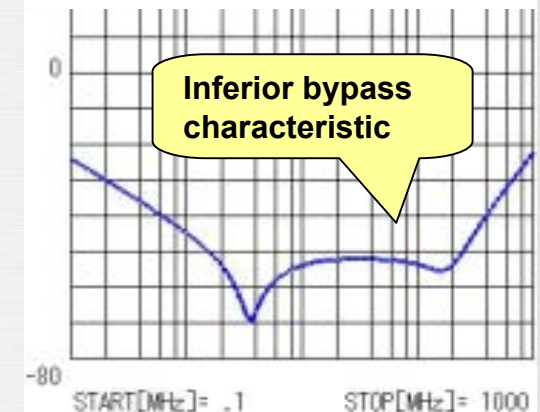
## Bypass characteristic of capacitor only



## Inductor A in use



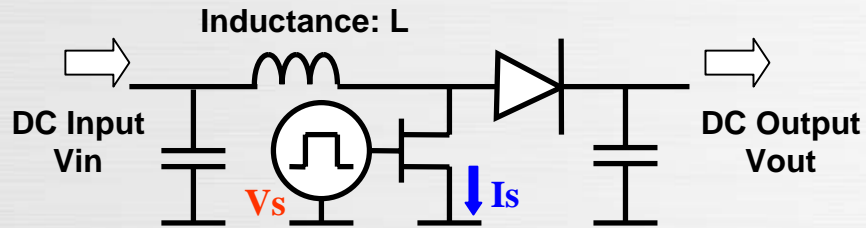
## Inductor B in use



In case of power supply choke application, it should take full advantage of **impedance characteristic** in terms of designing of bypass circuit. Since impedance characteristic is degraded by **DC bias**, it should be paid attention to see if the required value left under operational circumstances comparing with **self-resonance characteristic**.

# Example of the Influence on Inductor's DC Bias Characteristic of Power Supply Switching Circuit Application

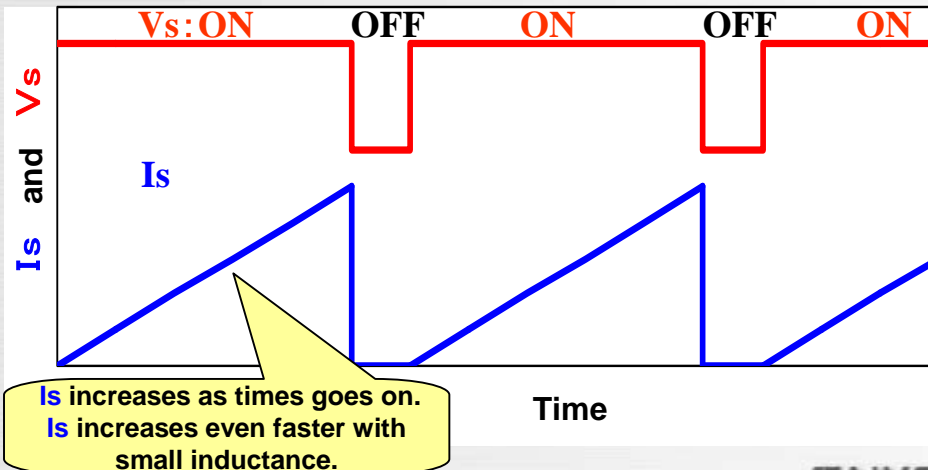
## Example of step-up power supply circuit



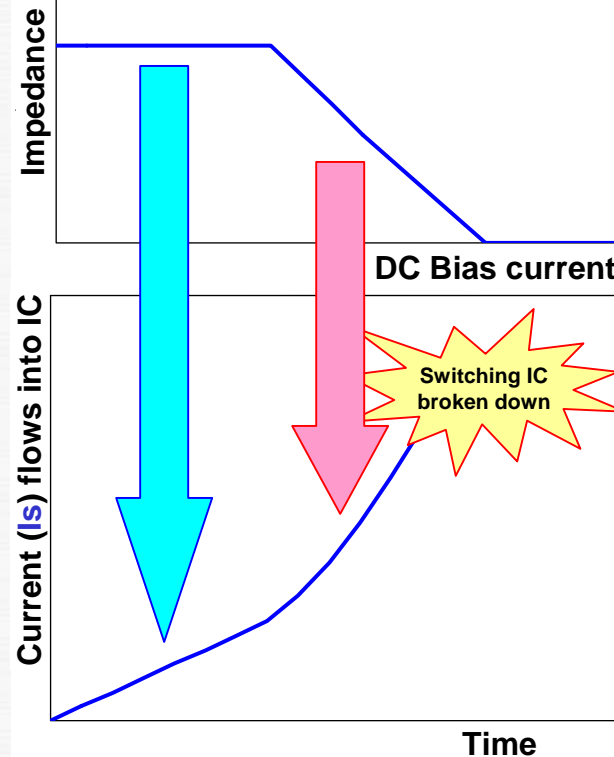
While  $V_s$  turned on,  $I_s$  flows to IC and then voltage is raised by inductor. When  $V_s$  being off, it is added onto the input DC and then Output DC is up-converted.

When  $V_s$  is being on,  $V_{in} = L \cdot di/dt$ , solving for this →  
 $I_s = V_{in} / L \cdot t$

$I_s$  gradually increases as  $V_s$  turned on, it increases rapidly with small inductance. It is important to know of the tolerance current when selecting an inductor for the power supply circuit.



## General relationship between DC bias characteristic and $I_s$



As DC bias current increases, the inductance starts decreasing.

DC bias current passes at some point, inductance drops suddenly.

When DC bias current passes the tolerance current, (for the worst case scenario) the switching IC is broken down.

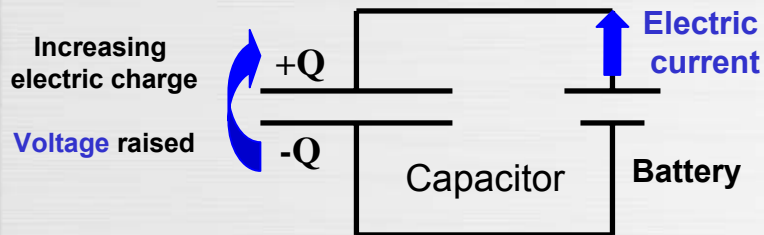
Switching interval is shortened by high frequency power supply IC, and therefore large inductance is no longer needed for IC.

Addition to this, flat DC bias characteristic isn't ideal for all kinds of circuit. It would be better to match a specific DC bias characteristic with IC and power supply demand.

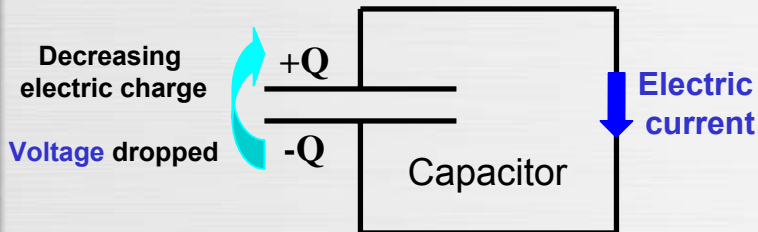


# Coffee Break “The Charging and Discharging Mechanisms of Capacitor”

## Charging mechanism



## Discharging mechanism



A time-varying electric charge induces electric current.

$$-I = dQ/dt$$

Capacitance is the constant of proportion derived from the relationship between the quantity of electric charge and voltage.

$$Q = C \cdot V$$

The relationship among voltage, electric current and capacitance

$$-V = 1/C \cdot \int i dt \text{ or } -I = C \cdot dV/dt$$

The equivalent relationship for inductor

$$-V = L \cdot di/dt$$

Apply **voltage** to a capacitor, **electronic charge** is built up in the inside of capacitor. On the other hand, when both sides of external electrodes are short-circuited, the capacitor discharges the built-up electronic charge.

The quantity of electronic charge is proportional to voltage. (In case with inductor, **an electronic current** creates **magnetic flux**. The quantity of magnetic flux is proportional to electronic current.)

Capacitor's **capacitance** is the constant of proportion between the quantity of electronic charge and voltage. (In case with inductor, **inductance** is the constant of proportion from magnetic flux and electronic current.

A **time-varying** electric charge or discharge induces electric current. In case with inductor, a time-varying magnetic flux induces electric voltage.

**- Chapter 3 -**

# **Electro-Magnetic Compatibility (EMC)**

## The Different Types of Noise

	Contents	Countermeasure components
<b>Radiation noise</b>	It leaks out as an electromagnetic wave. The sources are signal line and power line. There are restrictions in countries. (VCCI, FCC, CISPR, EN, etc.)	Mainly ML Ferrite Chip Beads BK series, Rectangular Ferrite Chip Beads (High Current) FB series M type. Resistors and capacitors may also be used.
<b>Conduction noise (noise terminal voltage)</b>	It runs through DC power line, i.e. switching noise, etc. The sources are DC-DC power supply converter, etc.	Mainly Surface Mount High Current Inductors NP series, Wound Chip Inductors LB series and such ferrite components and capacitors for DC-DC, etc.
<b>Ripple voltage (current)</b>	A fluctuation by voltage drop occurred when IC operates. It becomes a problem at power line with high power consumption for CPU, etc.	Mainly capacitors
<b>Electrostatic</b>	A discharge phenomenon, which is caused by friction charge. It causes element destruction and malfunctions.	Mainly Chip Varistors and Diodes. Capacitors and Beads may also be used.
<b>Surge noise</b>	Instantaneous high voltage and current. It is occurred by natural phenomenon (eg. thunderstorm), inserting and removing a cable, etc.	Spark Gaps and Varistors. Beads and Resistors for low voltage.



## Global Standard: CISPR

Japan: VCC class2  
(Consumer Equipment)

U.S.A.: FCC part15

Europe: EN55022

Other countries: Setting regulation based on CISPR



Regulation of the frequency band is between 30MHz to 1000MHz for VCCI.  
Others are referred on the next page.

## **1. CISPR 11 Group 2 Class B (1999 industry, chemistry, medical)**

**For equipment with embedded frequency of 400MHz and above**

**Regulated frequency: 1-2.4GHz band**

**Standard: 70dBuV/m and below (3m electric field intensity)**

## **2. CISPR 22 CIS/G/210/CD (2001 IT equipment)**

**For equipment with embedded frequency of 200MHz and above**

**Regulated frequency: 1-2.7GHz band**

**Standard: Average of 50dBuV/m and below,**

**Max 70dBuV/m and below (3m electric field intensity)**

## **3. FCC Part 15 (IT equipment)**

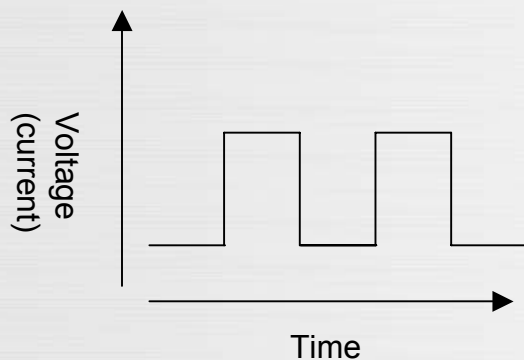
**Measurement up to 2GHz is required for an operation  
between 108 to 500MHz band.**

**Measurement up to 5GHz is required for an operation  
between 500 to 1000MHz band.**

# Mechanism of Radiation Noise 1

## Digital waveform

Measurement system: Oscilloscope

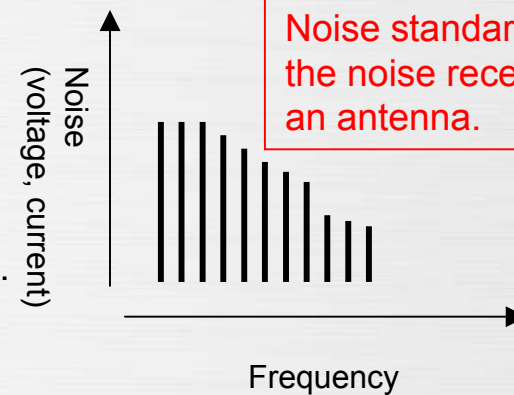


Fourier transform

Time axis is transformed to frequency.

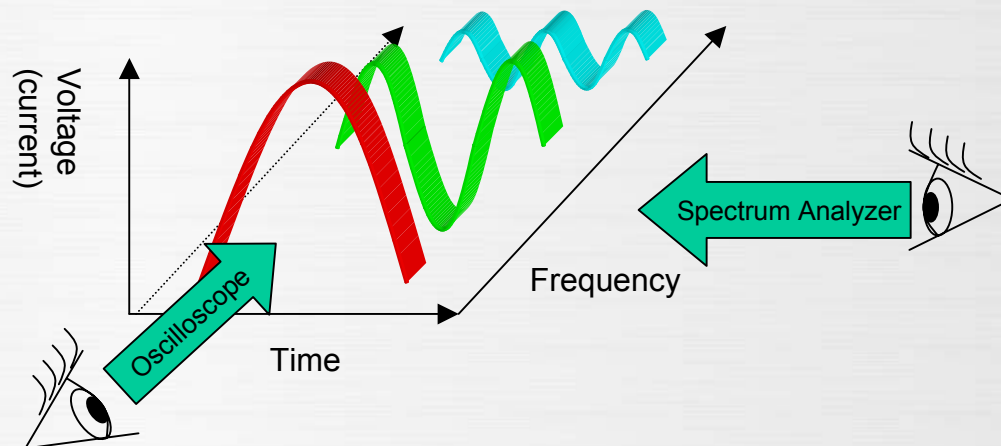
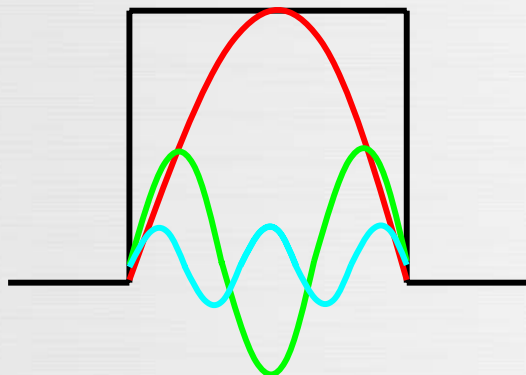
## Spectrum

Measurement system: Spectrum Analyzer



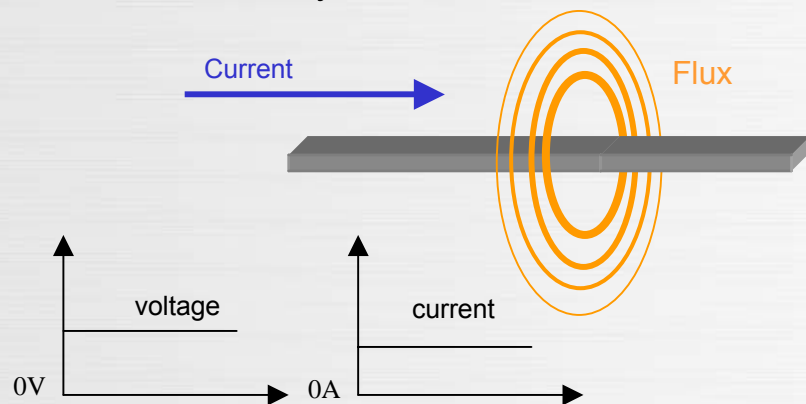
Noise standard restricts the noise received with an antenna.

Digital wave is formed by various frequencies.

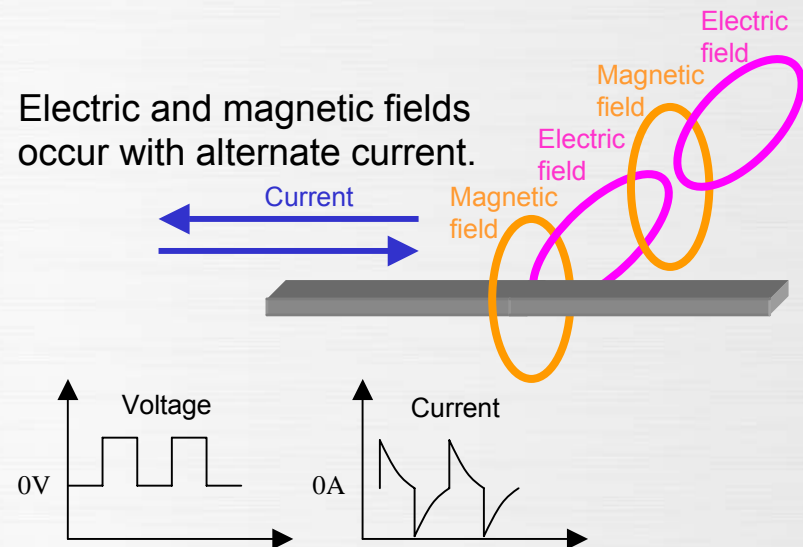


## Mechanism of Radiation Noise 2

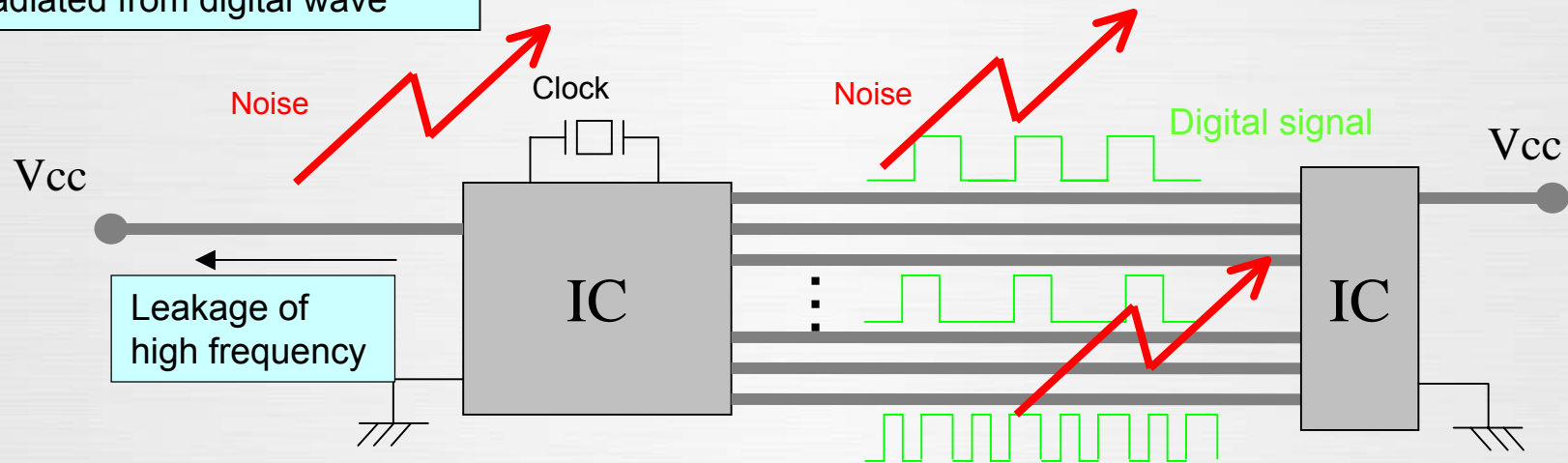
Flux occurs only with direct current.



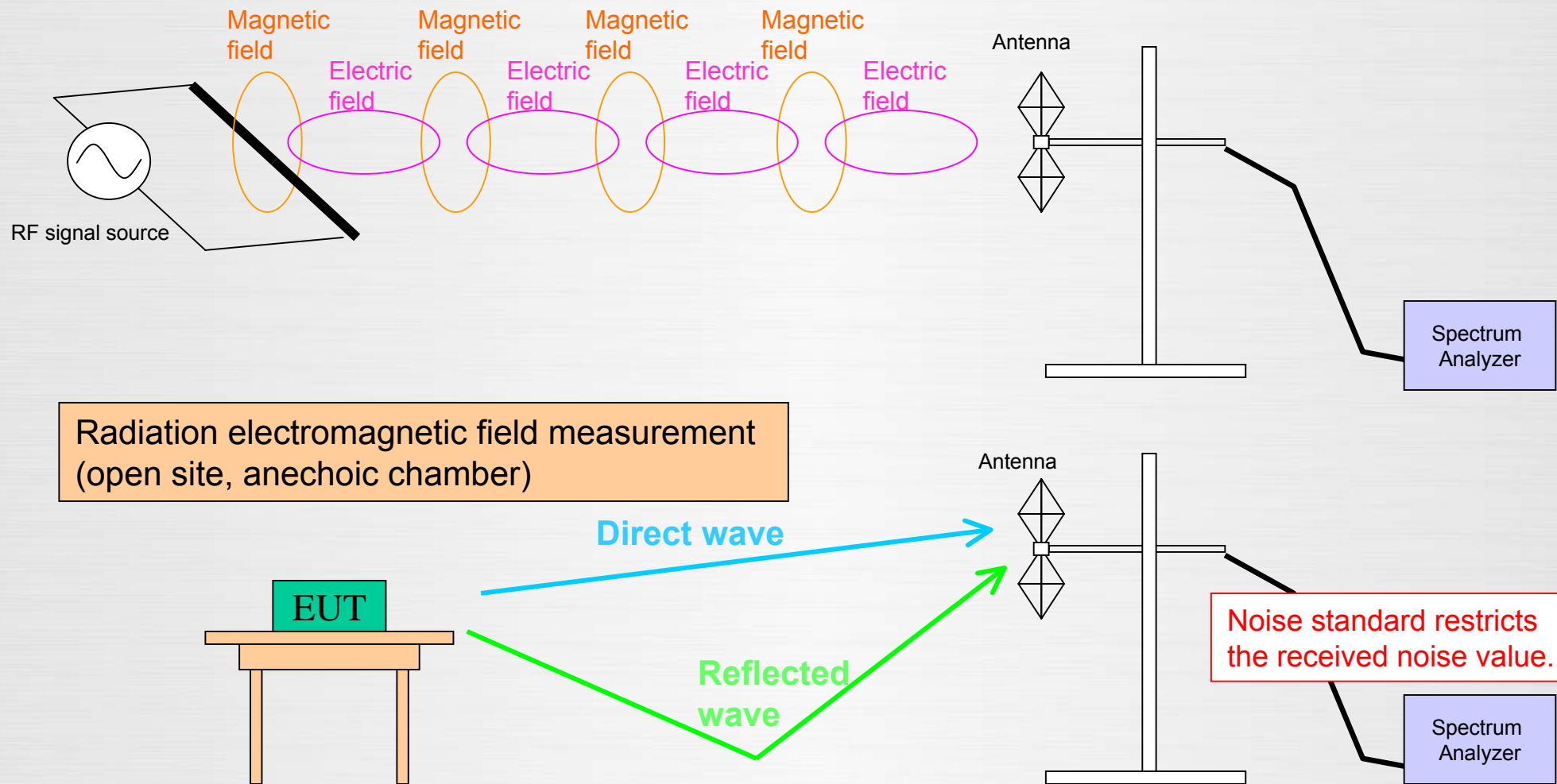
Electric and magnetic fields occur with alternate current.



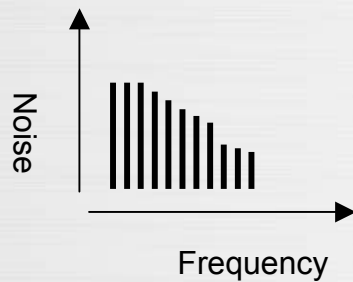
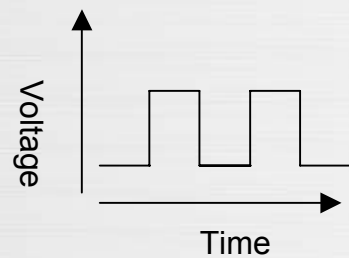
Radiated from digital wave



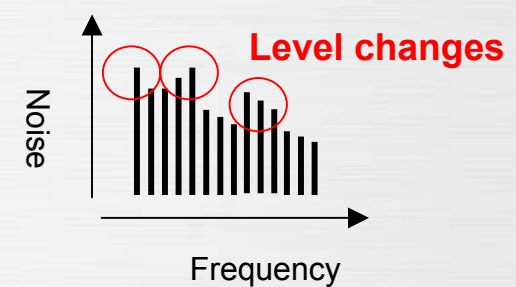
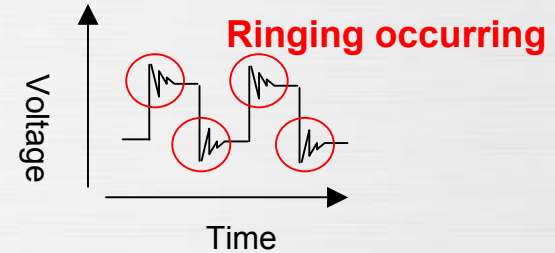
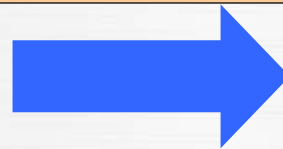
# Mechanism of Radiation Noise 3



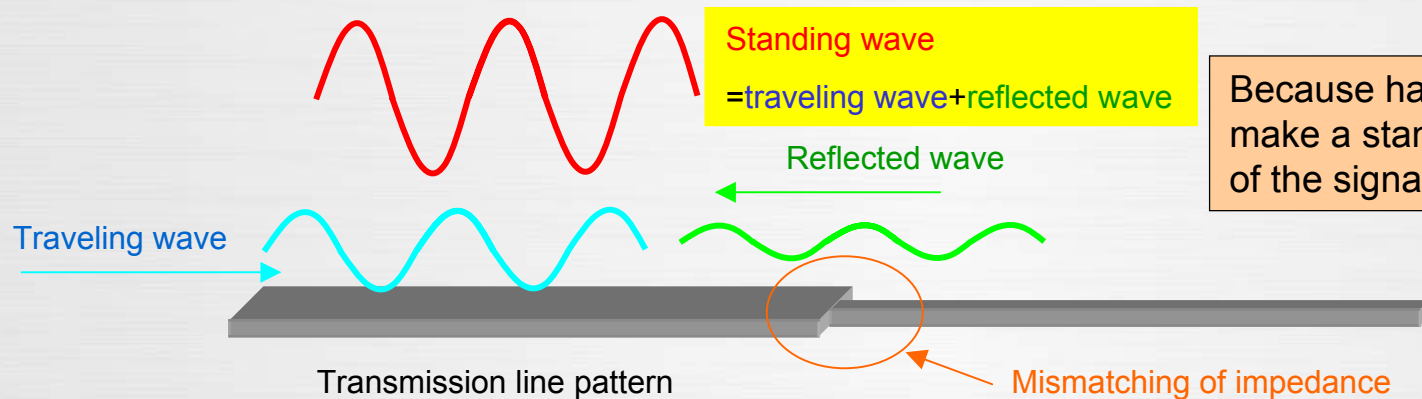
# Mechanism of Radiation Noise 4



**Spectrum changes with waveform distortion.**



**Cause: mismatching of transmission line**



Because harmonics of a digital signal make a standing wave, the emission of the signal increases as noise.



*Fin.*

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